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# South & Central America 3D Stacking Market Forecast to 2031 - Regional Analysis by Interconnecting Technology (Through-Silicon Via, Monolithic 3D Integration, and 3D Hybrid Bonding), Device Type (Memory Devices, MEMS/Sensors, LEDs, Imaging & Optoelectronics, and Others), and End User (Consumer Electronics, Telecommunication, Automotive, Manufacturing, Healthcare, and Others)

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## Abstracts

The South & Central America 3D stacking market was valued at US$ 69.93 million in 2023 and is expected to reach US$ 122.69 million by 2031; it is anticipated to register a CAGR of 7.3% from 2023 to 2031.

Surge in Demand for High-Bandwidth Memory Fuels South & Central America 3D Stacking Market

High-bandwidth memory (HBM), which reaches extremely high density by stacking numerous dynamic random-access memory (DRAMs) vertically, is distinguished by rapid data processing and low power consumption. It is essential in high-performance computing (HPC), such as generative AI, which requires processing enormous amounts of data at significantly fast speeds. Samsung Electronics 12-layer stacked HBM uses next-generation 3D stacking packaging technique to boost performance and yield. With a processing speed of 6.4Gbps and a bandwidth of 819 GB/s, HBM3 is 1.8 times faster than the previous-generation DRAM while using 10% less power. The demand for HBM in high-performance computing applications encourages market players to increase their production. For instance, in March 2024, SK HYNIX INC started volume production

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of HBM3E1, the newest AI memory product with ultra-high performance. HBM3E is designed for an AI system that processes a huge amount of data quickly. The high-bandwidth memory is used by various industries, including telecommunication, automotive, healthcare, and manufacturing, for high-speed data processing.

HBM utilizes 3D stacking technology, allowing the stacking of multiple layers of chips using vertical channels known as through-silicon vias (TSVs). This enables a greater number of memory chips to be packed into a smaller space, minimizing the distance data must travel between the memory and processor. HBM can help lengthen battery life and reduce energy consumption by offering sustainable benefits to users. This supports users in decreasing the amount of power required to transmit data between memory and processor. Therefore, the surge in demand for high-speed data processing and low-power consumption memories is expected to create lucrative opportunities for the 3D stacking market growth during the forecast period.

South & Central America 3D Stacking Market Overview

The South & Central America 3D stacking market is segmented into Brazil, Argentina, and the Rest of South & Central America. The growing demand for CMOS image sensors in machine vision systems fuels the need for 3D stacking. The 3D stacking market growth in SAM is majorly driven by the rising demand for high-quality cameras in smartphones and tablets and the growing application of image sensors in various sectors such as medical diagnostic & image sensors and automotive. Also, the consumer electronics industry is proliferating in the region due to increasing demand for electronic devices across healthcare, consumer electronics, and manufacturing sectors. South & Central American countries such as Argentina, Chile, Brazil, and Colombia are major players in the consumer electronics industry. The growing number of consumer electronics require 3D stacking for various purposes. For example, 3D stacking is a transformative technology in consumer electronics that enables the creation of more powerful, efficient, and compact devices. Therefore, with the increase in the electronic industry, the demand for 3D stacking is also increasing in South & Central America.

South & Central America 3D Stacking Market Revenue and Forecast to 2031 (US$ Million)

South & Central America 3D Stacking Market Segmentation

The South & Central America 3D stacking market is categorized into interconnecting technology, device type, end user, and country.

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Based on interconnecting technology, the South & Central America 3D stacking market is segmented into through-silicon via, monolithic 3D integration, and 3D hybrid bonding. The through-silicon via segment held the largest market share in 2023.

By device type, the South & Central America 3D stacking market is segmented into memory devices, mems/sensors, LEDs, imaging & optoelectronics, and others. The memory devices segment held the largest market share in 2023.

In the terms of end user, the South & Central America 3D stacking market is segmented into consumer electronics, telecommunication, automotive, manufacturing, healthcare, and others. The consumer electronics segment held the largest market share in 2023.

By country, the South & Central America 3D stacking market is segmented into Brazil, Argentina, and the Rest of South & Central America. Argentina dominated the South & Central America 3D stacking market share in 2023.

Samsung Electronics Co Ltd; Intel Corp; Texas Instruments Inc; Advanced Micro Devices Inc.; 3M Co.; and Globalfoundries Inc are some of the leading companies operating in the South & Central America 3D stacking market.

Reason to buy

- Save and reduce time carrying out entry-level research by identifying the growth, size, leading players, and segments in the South & Central America 3D stacking market.
- Highlights key business priorities in order to assist companies to realign their business strategies.
- The key findings and recommendations highlight crucial progressive industry trends in the South & Central America 3D stacking market, thereby allowing players across the value chain to develop effective long-term strategies.
- Develop/modify business expansion plans by using substantial growth offering developed and emerging markets.
- Scrutinize in-depth South & Central America market trends and outlook coupled with the factors driving the South & Central America 3D stacking market, as well

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as those hindering it.

Enhance the decision-making process by understanding the strategies that underpin commercial interest with respect to client products, segmentation, pricing, and distribution.

The List of Companies - South & Central America 3D Stacking Market

Samsung Electronics Co Ltd

Intel Corp

Texas Instruments Inc

Advanced Micro Devices Inc

3M Co

Globalfoundries Inc

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# Contents

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## 9. SOUTH & CENTRAL AMERICA 3D STACKING MARKET ANALYSIS - BY END USER



## 10. SOUTH AND CENTRAL AMERICA 3D STACKING MARKET -COUNTRY ANALYSIS

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## 11. COMPETITIVE LANDSCAPE



## 12. INDUSTRY LANDSCAPE



## 13. COMPANY PROFILES

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# List Of Tables

## LIST OF TABLES

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# List Of Figures

## LIST OF FIGURES

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